

DRAWING NUMBER LDS-AA102RI	REV
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ELECTRO-OPTICAL CHARACTERISTICS $T_A = 25^\circ\text{C}$ $I_f = 10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		565 (GREEN)		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu A$
AXIAL INTENSITY		5600		μcd	$I_f=10 mA$
EMITTED COLOR:	GREEN				
FONT COLOR:	GREY				
SEGMENT COLOR:	MILKY WHITE	DIFFUSED			

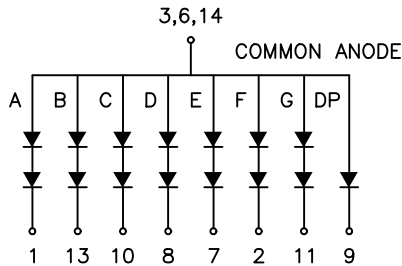
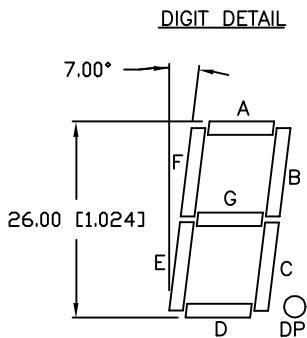
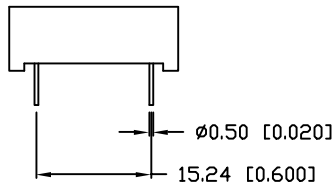
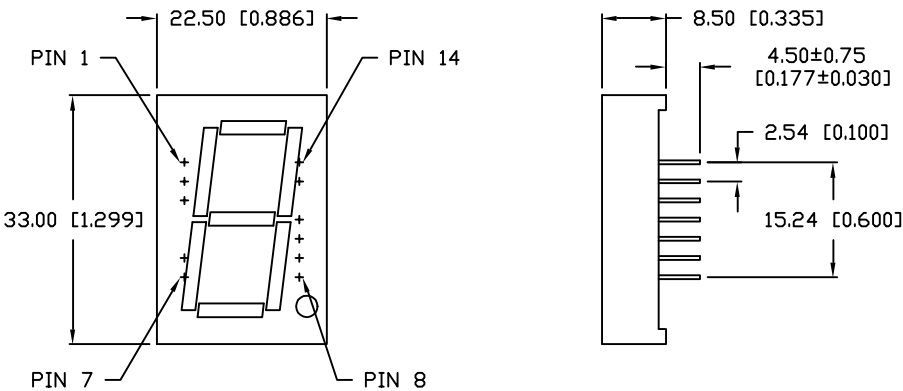
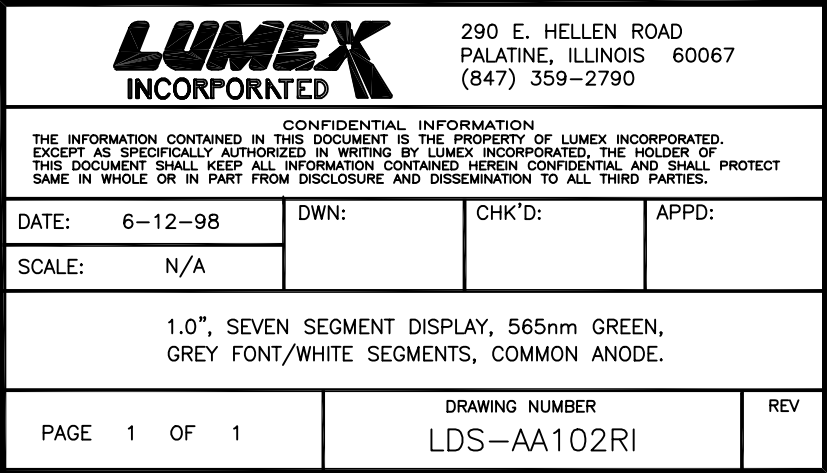
LIMITS OF SAFE OPERATION AT 25°C PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	- 1.2	mW/°C
OPERATING, STORAGE TEMP.	-20 TO +80	°C
SOLDERING TEMP.	+260	°C
2.0mm FROM BODY		3 SEC. MAX

* $t < 10 \mu S$

RELIABILITY NOTE

OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



NOTE: NO PIN 4,5, & 12

UNLESS OTHERWISE SPECIFIED TOLERANCE IS $\pm .25\text{mm}$ ($\pm 0.010"$)

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